



## ***Press Release***

### **For Immediate Release**

Wednesday, 04/10/2014

## **YINCAE Advanced Materials, LLC Announces Industry Breakthrough Products at IPC/APEX 2014 Expo**

(Albany, NY) April 11, 2014 - YINCAE Advanced Materials, LLC announced its new, innovative product lineup for 2014 at the IPC APEX Expo in Las Vegas. In an interview with I-Connect007's Guest Editor Mark Thompson, Dr. Wusheng Yin, CEO, of YINCAE Advanced Materials discussed three industry changing YINCAE products:

1. SMT256 – Solder Joint Encapsulant: a replacement for traditional underfill used at the board level. Dr. Yin stated that the product is “5-to-10 times as strong” as the bond obtained through existing soldering / underfilling methods. The product is highly suited for board-level and package-level applications like smart phones that require high-speed and high durability, and is the only encapsulant approved and currently in use by major industry leaders.
2. LEN66AL – Fast-Bonding UV Curable Optoelectric Die Attachment Adhesive designed specifically for chip attachment. The product not only makes the manufacturing process easy, but also dramatically increases process yield. This product provides bubble-free optical coverage and outstanding moisture resistance. Its bonding flexibility easily dissipates the thermal stress from different CTE substrates. It meets MIL-I46058C and IPC-CC-830 standards and is in full compliance with the RoSH Directive.

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3. ACP120 – The ACP 120 Series is an Anti-oxidation Solderable Coating for Metals. This product is an excellent Nanofilm Gold Replacement. This product is designed as an anti-corrosion and anti-rusting coating for metal surfaces such as nickel, steel, aluminum and other metals and solderable surfaces on which solder paste, solder preform or a solder ball can be soldered. The complete video interview can be viewed at <http://www.realtimewith.com/> and searching for “YINCAE.”

These products provide manufacturers with innovative products to solve complex manufacturing problems while reducing costs.

YINCAE Advanced Materials, LLC is a leading manufacturer and supplier of high-performance coatings, adhesives and encapsulants used in the computer microchip and optoelectronics industries. Our manufacturing operations and headquarters are located in Albany, NY USA, with technical sales and support available through a worldwide sales and service organization.

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